

3W UV Power LED Technical Datasheet Version: 1.8

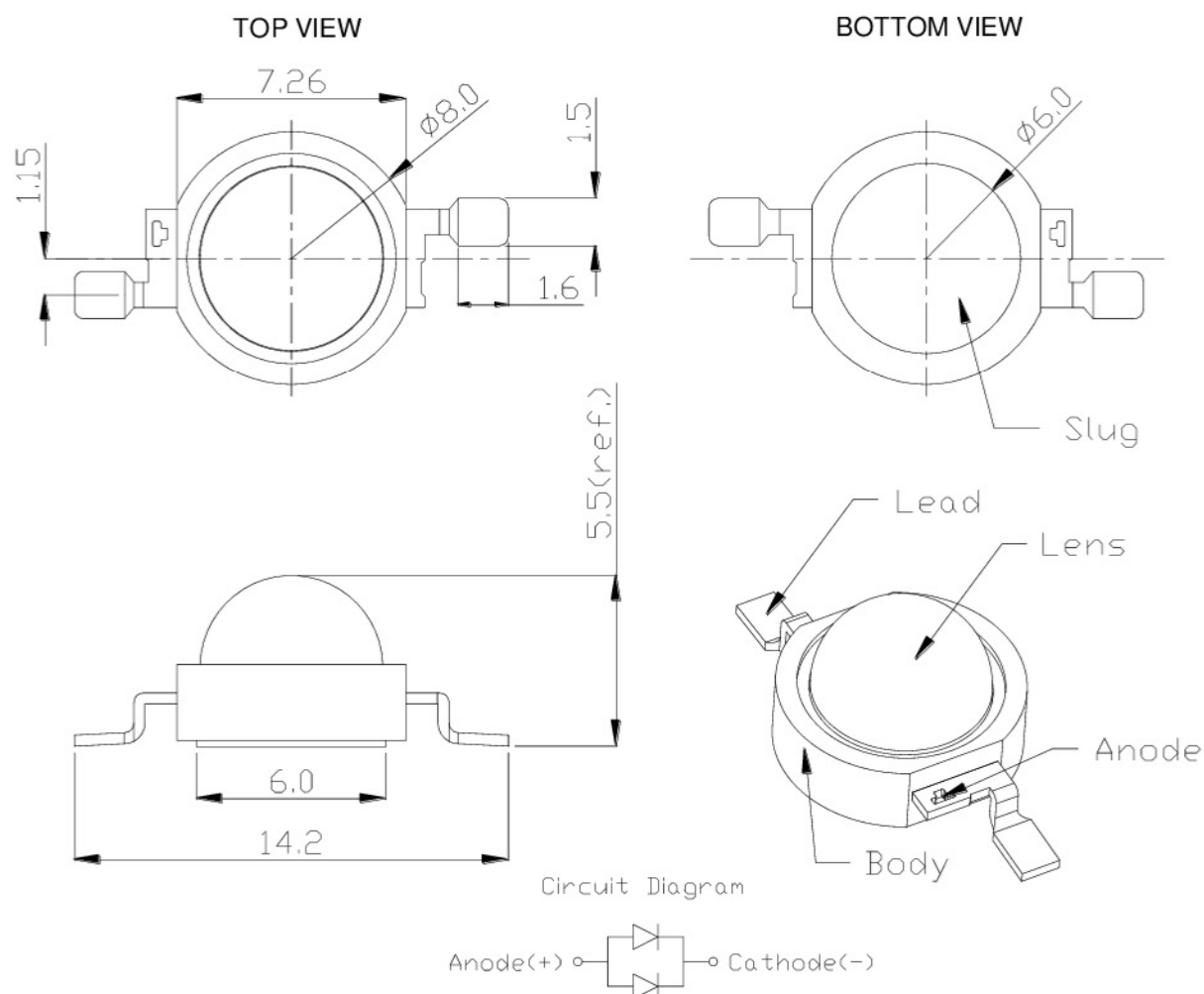
Features

- Instant light (less than 100ns)
- Lead free reflow soldering
- RoHS compliant
- Cool beam, safe to the touch

Typical Applications

- UV gluing, UV curing, UV marking
- UV drying of printing inks and lacquers
- Currency inspection
- Forensic analysis - urine, protein stains
- Leak detection using fluorescent dyes
- Detects fluorescing minerals and gems

Emitter Mechanical Dimensions

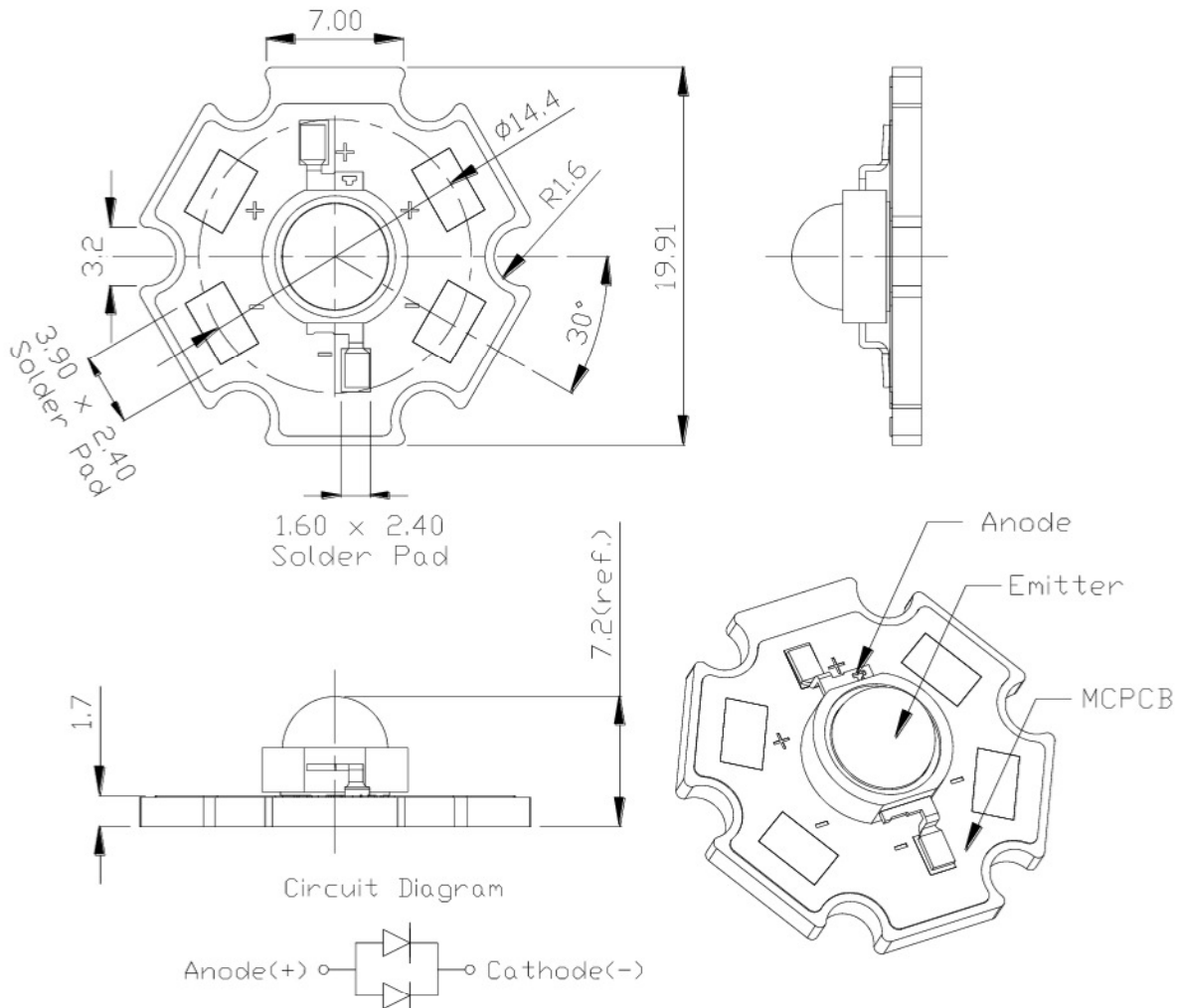


Notes:

1. The Anode side of the device is denoted by a hole in the lead frame.
2. Electrical insulation between the case and the board is required --- slug of device is not electrically neutral. Do not electrically connect either the anode or cathode to the slug.
3. Drawing not to scale.
4. All dimensions are in millimeters.
5. All dimensions without tolerances are for reference only.
6. Please do not bend the leads of the LED, otherwise it will damage the LED.
7. **Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.**

*The appearance and specifications of the product may be modified for improvement without notice.

Star Mechanical Dimensions



Notes:

1. Slots in aluminum-core PCB for M3 or #4 mounting screw.
2. Electrical interconnection pads labeled on the aluminum-core PCB with "+" and "-" to denote positive and negative, respectively. All positive pads are interconnected, as are all negative pads, allowing for flexibility in array interconnection.
3. Drawing not to scale.
4. All dimensions are in millimeters.
5. All dimensions without tolerances are for reference only.
6. **Please do not use a force of over 3kgf impact or pressure on the lens of the LED, otherwise it will cause a catastrophic failure.**

*The appearance and specifications of the product may be modified for improvement without notice.

Flux Characteristics at 700mA, $T_J = 25^\circ\text{C}$

| Radiation Pattern | Color | Part Number | | Radiometric Power (mW) | |
|-------------------|-------|-------------|-----------|------------------------|---------|
| | | Emitter | Star | Minimum | Typical |
| Lambertian | UV | WEPUV3-E2 | WEPUV3-S2 | 635 | 900 |

- Please do not drive at rated current more than 1 second without proper heat sink.

Electrical Characteristics at 700mA, $T_J = 25^\circ\text{C}$

| Color | Forward Voltage V_F (V) | | | Thermal Resistance Junction to Slug ($^\circ\text{C}/\text{W}$) |
|-------|---------------------------|------|------|--|
| | Min. | Typ. | Max. | |
| UV | 2.85 | 3.4 | 4.1 | 8 |

Optical Characteristics at 700mA, $T_J = 25^\circ\text{C}$

| Color | Min. | Peak Wavelength λ_p | | Total included Angle (degrees) $\theta_{0.90V}$ | Viewing Angle (degrees) $2\theta_{1/2}$ |
|-------|--------|-----------------------------|--------|---|---|
| | | Typ. | Max. | | |
| UV | 390 nm | 400 nm | 410 nm | 180 | 130 |

Absolute Maximum Ratings

| Parameter | UV |
|--|---|
| DC Forward Current (mA) | 700 |
| Peak Pulsed Forward Current (mA) | 1000 (less than 1/10 duty cycle@1KHz) |
| Average Forward Current (mA) | 700 |
| ESD Sensitivity (HBM per MIL-STD-883E Method 3015.7) | > ±500V |
| LED Junction Temperature (°C) | 120°C |
| Operating Board Temperature at Maximum DC Forward Current | -40°C - 100°C |
| Storage Temperature | -40°C - 120°C |
| Soldering Temperature | 260°C |
| Allowable Reflow Cycles | 3 |
| Reverse Voltage | Not designed to be driven in reverse bias |

Reverse Voltage

Radiometric Power Bin Structure

| Color | Bin Code | Minimum Radiometric Power (mW) | Maximum Radiometric Power (mW) | Available Color Bins |
|-------|----------|-----------------------------------|-----------------------------------|-------------------------|
| UV | S | 635 | 755 | [1] |
| | T | 755 | 875 | 2,3,4 [1] |
| | U | 875 | 1050 | 2,3,4 [1] |
| | V | 1050 | 1225 | [1] |

● The flux bin of the product may be modified for improvement without notice.

● [1] The rest of color bins are not 100% ready for order currently. Please ask for quote and order possibility.

Peak Wavelength Bin Structure

| Color | Bin Code | Minimum Peak Wavelength (nm) | Maximum Peak Wavelength (nm) |
|-------|----------|---------------------------------|---------------------------------|
| UV | 1 | 390 | 395 |
| | 2 | 395 | 400 |
| | 3 | 400 | 405 |
| | 4 | 405 | 410 |

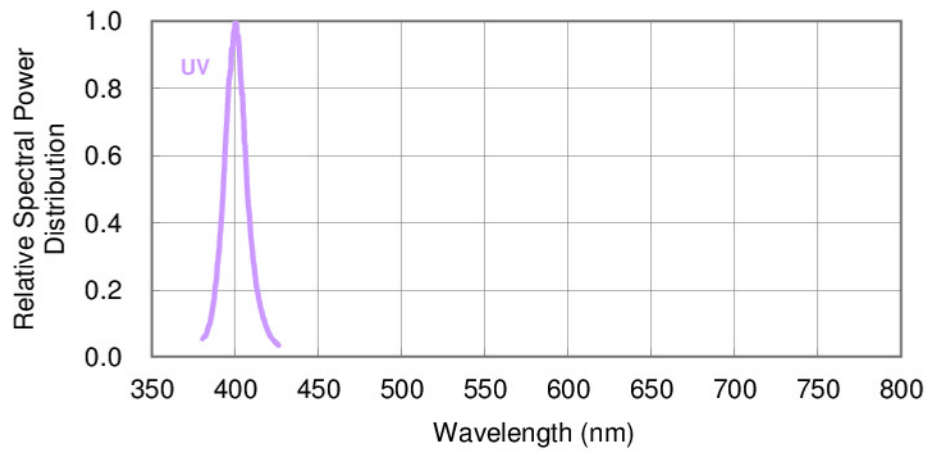
Forward Voltage Bin Structure

| Color | Bin Code | Minimum Voltage (V) | Maximum Voltage (V) |
|-------|----------|---------------------|---------------------|
| UV | A | 2.85 | 3.10 |
| | B | 3.10 | 3.35 |
| | D | 3.35 | 3.60 |
| | E | 3.60 | 3.85 |
| | F | 3.85 | 4.10 |

Note: Although several bins are outlined, product availability in a particular bin varies by production run and by product performance. Not all bins are available in all colors.

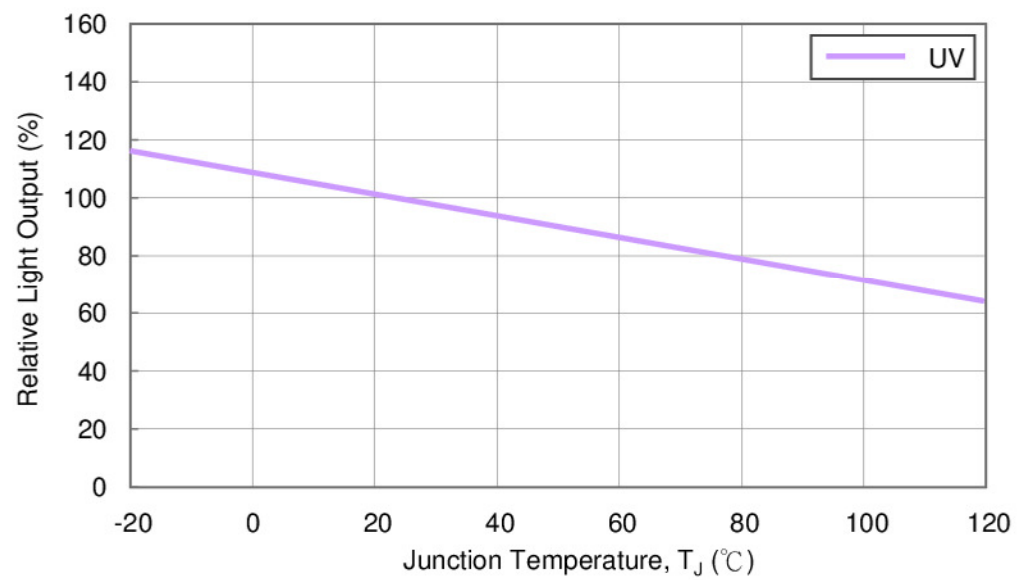
Color Spectrum, $T_J = 25^\circ\text{C}$

1. UV



Light Output Characteristics

Relative Light Output vs. Junction Temperature at 700mA



Forward Current Characteristics, $T_j=25^\circ\text{C}$

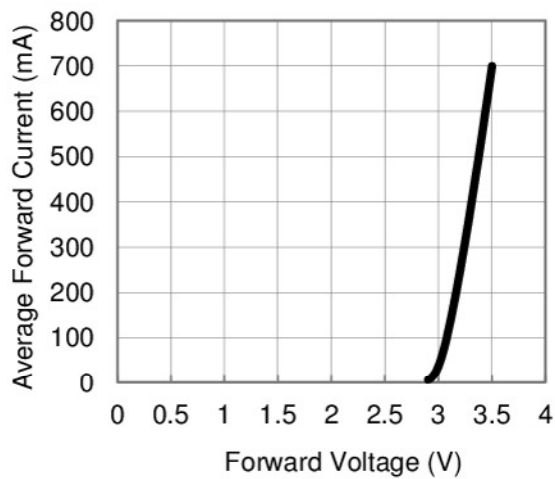


Fig 1. Forward Current vs. Forward Voltage

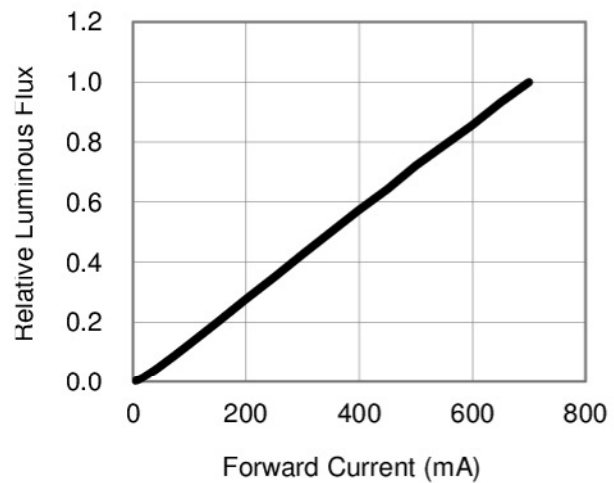
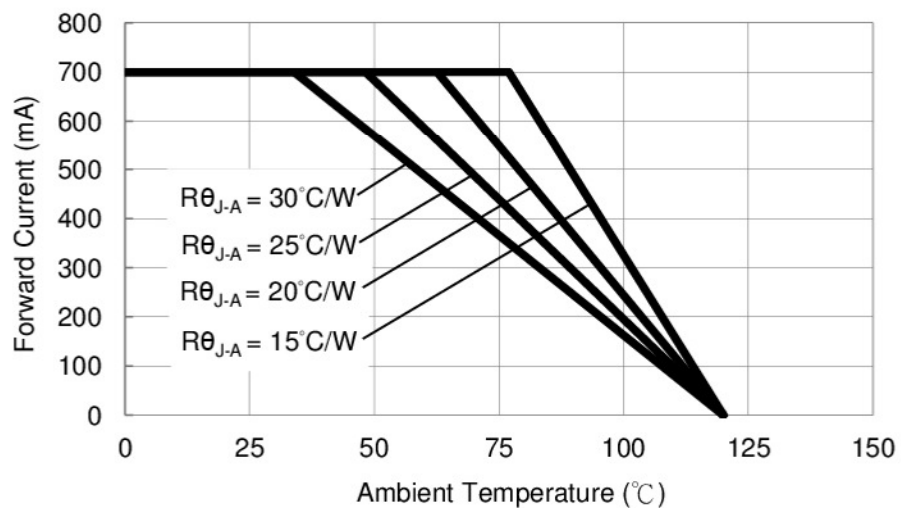


Fig 2. Relative Luminous Flux vs. Forward Current at $T_j=25^\circ\text{C}$ maintained.

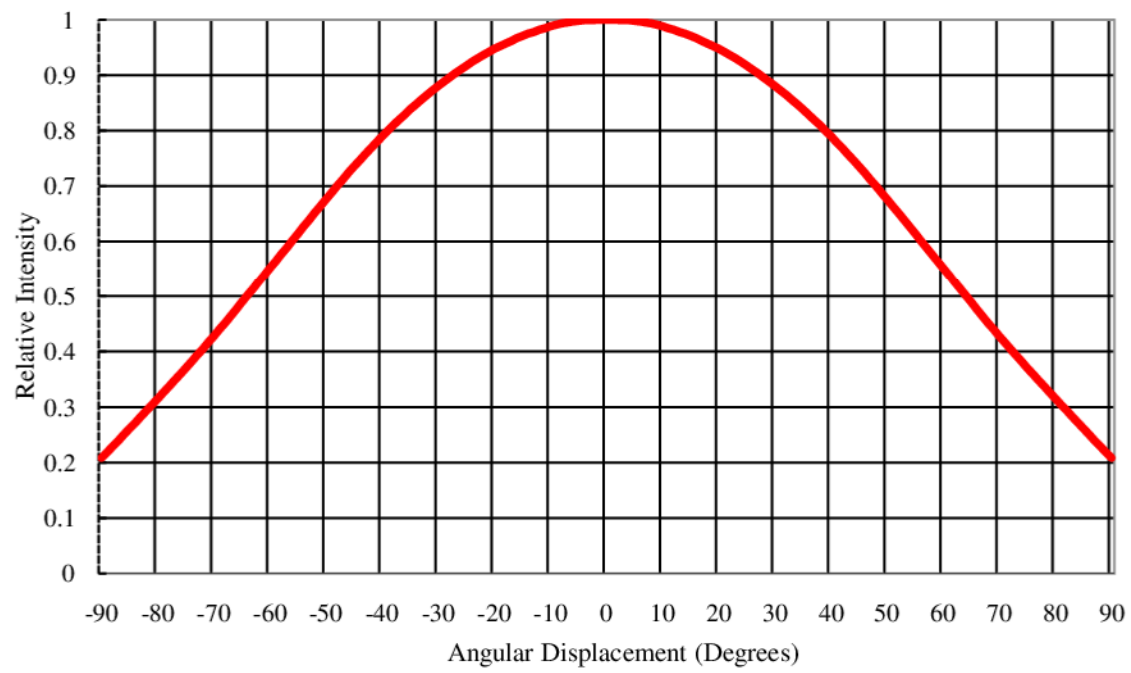
Ambient Temperature vs. Maximum Forward Current

1. UV ($T_{JMAX} = 120^\circ\text{C}$)



Typical Representative Spatial Radiation Pattern

Lambertian Radiation Pattern



Qualification Reliability Testing

| Stress Test | Stress Conditions | Stress Duration | Failure Criteria |
|---|--|-----------------|----------------------------|
| Room Temperature Operating Life (RTOL) | 25°C, $I_F = \text{max DC}$ (Note 1) | 1000 hours | Note 2 |
| Wet High Temperature Operating Life (WHTOL) | 85°C/60%RH, $I_F = \text{max DC}$ (Note 1) | 1000 hours | Note 2 |
| Wet High Temperature Storage Life (WHTSL) | 85°C/85%RH, non-operating | 1000 hours | Note 2 |
| High Temperature Storage Life (HTSL) | 110°C, non-operating | 1000 hours | Note 2 |
| Low Temperature Storage Life (LTSL) | -40°C, non-operating | 1000 hours | Note 2 |
| Non-operating Temperature Cycle (TMCL) | -40°C to 120°C, 30 min. dwell, <5 min. transfer | 200 cycles | Note 2 |
| Non-operating Thermal Shock (TMSK) | -40°C to 120°C, 20 min. dwell, <20 sec. transfer | 200 cycles | Note 2 |
| Mechanical Shock | 1500 G, 0.5 msec. pulse, 5 shocks each 6 axis | | Note 3 |
| Natural Drop | On concrete from 1.2 m, 3X | | Note 3 |
| Variable Vibration Frequency | 10-2000-10 Hz, log or linear sweep rate, 20 G about 1 min., 1.5 mm, 3X/axis | | Note 3 |
| Solder Heat Resistance (SHR) | 260°C \pm 5°C, 10 sec. | | Note 3 |
| Solderability | Steam age for 16 hrs., then solder dip at 260°C for 5 sec. | | Solder coverage on lead |

Notes:

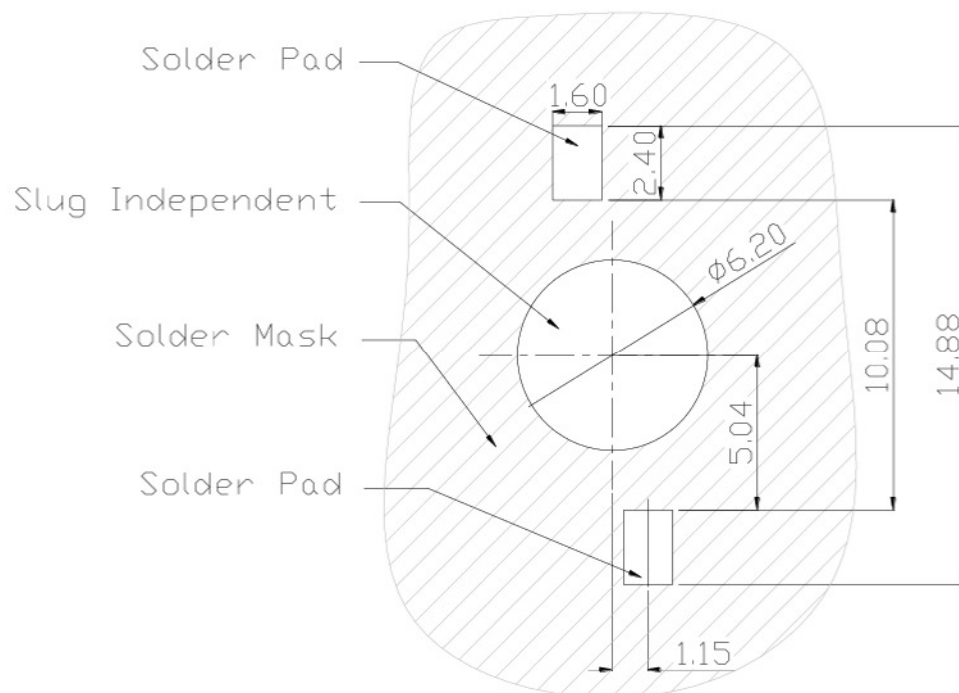
1. Depending on the maximum derating curve.
2. Criteria for judging failure

| Item | Test Condition | Criteria for Judgement | |
|---|-----------------------|------------------------|---------------------|
| | | Min. | Max. |
| Forward Voltage (V_F) | $I_F = \text{max DC}$ | - | Initial Level x 1.1 |
| Luminous Flux or Radiometric Power (Φ_V) | $I_F = \text{max DC}$ | Initial Level x 0.7 | - |

* The test is performed after the LED is cooled down to the room temperature.

3. A failure is an LED that is open or shorted.

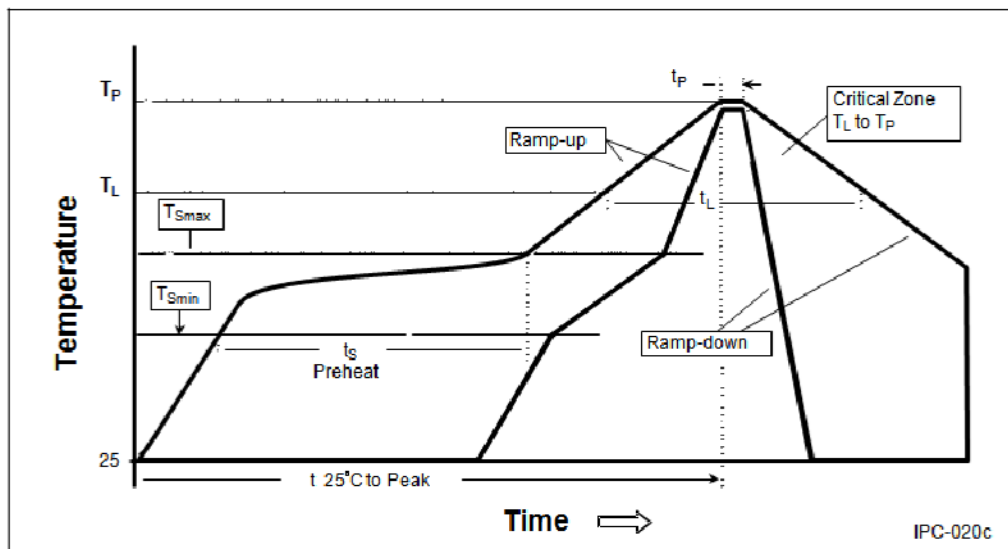
Recommended Solder Pad Design



- All dimensions are in millimeters.
- Electrical isolation is required between Slug and Solder Pad.

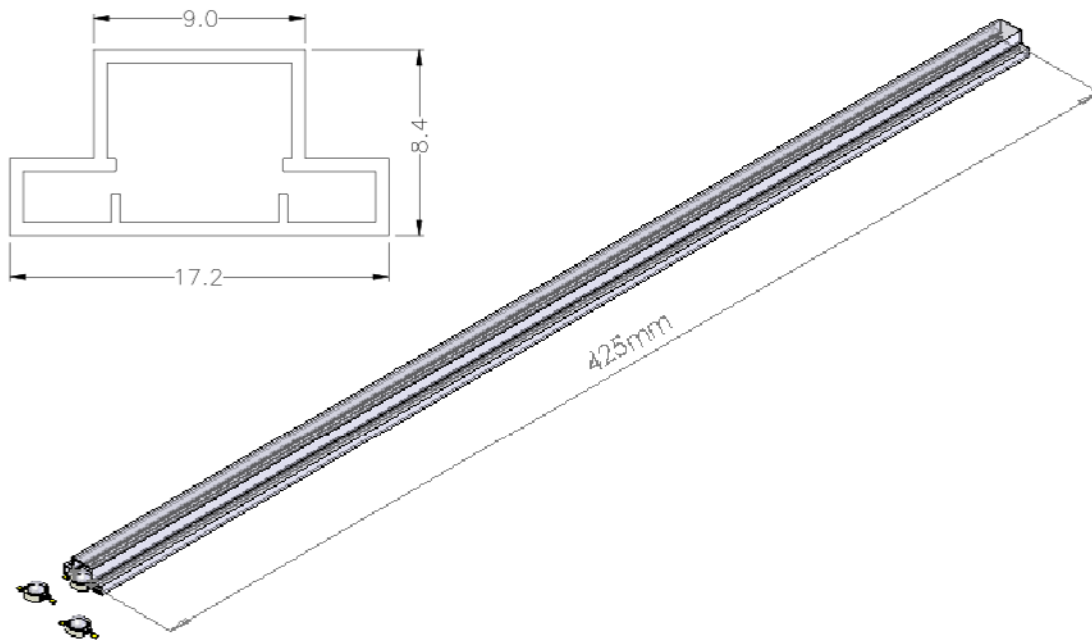
Reflow Soldering Condition

| Profile Feature | Sn-Pb Eutectic Assembly | Pb-Free Assembly |
|---|----------------------------------|----------------------------------|
| Average Ramp-Up Rate (T_{Smax} to T_P) | 3°C / second max. | 3°C / second max. |
| Preheat <ul style="list-style-type: none"> – Temperature Min (T_{Smin}) – Temperature Max (T_{Smax}) – Time (t_{Smin} to t_{Smax}) | 100°C 150°C 60-120 seconds | 150°C 200°C 60-180 seconds |
| Time maintained above: <ul style="list-style-type: none"> – Temperature (T_L) – Time (t_L) | 183°C 60-150 seconds | 217°C 60-150 seconds |
| Peak/Classification Temperature (T_P) | 240°C | 260°C |
| Time Within 5°C of Actual Peak Temperature (t_P) | 10-30 seconds | 20-40 seconds |
| Ramp-Down Rate | 6°C/second max. | 6°C/second max. |
| Time 25°C to Peak Temperature | 6 minutes max. | 8 minutes max. |

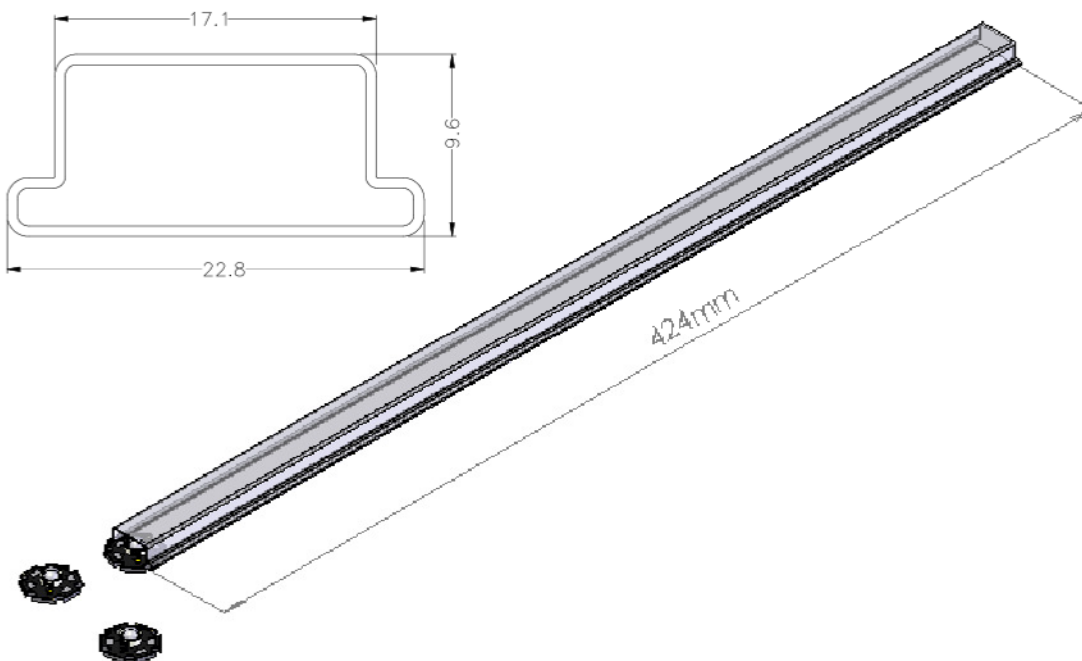


- We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.
- All temperatures refer to topside of the package, measured on the package body surface.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.

Emitter Tube Packaging



Star Tube Packaging



Notes:

1. Emitter 50 pieces per tube and Star 20 pieces per tube.
2. Drawing not to scale.
3. All dimensions are in millimeters.
4. All dimensions without tolerances are for reference only.

****Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration.**

The recommended storage conditions are temperature 5 to 30°C and humidity less than 40% RH.

Precaution for Use

- Storage
Please do not open the moisture barrier bag (MBB) more than one week. This may cause the leads of LED discoloration. We recommend storing WINGER LEDs in a dry box after opening the MBB. The recommended storage conditions are temperature 5 to 30 °C and humidity less than 40% RH. It is also recommended to return the LEDs to the MBB and to reseal the MBB.
- The slug is not electrically neutral. Therefore, we recommend to isolate the heat sink.
- The LEDs are sensitive to electrostatic discharge. Appropriate ESD protection measures must be taken when working with the LEDs. Non-compliance with ESD protection measures may lead to damage or destruction of the LEDs.
- **We recommend using the M705-S101-S4 solder paste from SMIC (Senju Metal Industry Co., Ltd.) for lead-free soldering.**
- Any mechanical force or any excess vibration shall not be accepted to apply during cooling process to normal temperature after soldering.
- Please avoid rapid cooling after soldering.
- Components should not be mounted on warped direction of PCB.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a heat plate should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When cleaning is required, isopropyl alcohol should be used.
- When the LEDs are illuminating, operating current should be decided after considering the package maximum temperature.
- The appearance, specifications and flux bin of the product may be modified for improvement without notice.

Handling of Silicone Lens LEDs

Notes for handling of silicone lens LEDs

- Please do not use a force of over 3kgf impact or pressure on the silicone lens, otherwise it will cause a catastrophic failure.
- The LEDs should only be picked up by making contact with the sides of the LED body.
- Avoid touching the silicone lens especially by sharp tools such as Tweezers.
- Avoid leaving fingerprints on the silicone lens.
- Please store the LEDs away from dusty areas or seal the product against dust.
- When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the silicone lens must be prevented.
- Please do not mold over the silicone lens with another resin. (epoxy, urethane, etc)

